SCLS109G - MARCH 1984 - REVISED APRIL 2004

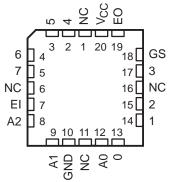
- Wide Operating Voltage Range of 2 V to 6 V
- Outputs Can Drive Up To 10 LSTTL Loads
- Low Power Consumption, 80-μA Max I_{CC}
- Typical t_{pd} = 16 ns
- ±4-mA Output Drive at 5 V
- Low Input Current of 1 μA Max
- Encode Eight Data Lines to 3-Line Binary (Octal)
- Applications Include:
 - n-Bit Encoding
 - Code Converters and Generators

description/ordering information

The 'HC148 devices feature priority decoding of the inputs to ensure that only the highest-order data line is encoded. These devices encode eight data lines to 3-line (4-2-1) binary (octal). Cascading circuitry (enable input EI and enable output EO) has been provided to allow octal expansion without the need for external circuitry. Data inputs and outputs are active at the low logic level. SN54HC148 ... J OR W PACKAGE SN74HC148 ... D, DW, N, OR NS PACKAGE (TOP VIEW)

	(• /	
4 [5 [6 [7 [EI [A2 [A1 [GND]	1 2 3 4 5 6 7 8	1 [.] 1(3 2 1] V _{CC}] EO] GS] 3] 2] 1] 0] A0
			_	

SN54HC148 . . . FK PACKAGE (TOP VIEW)



NC - No internal connection

ORDERING INFORMATION

TA	PACKAG	GE†	ORDERABLE PART NUMBER	TOP-SIDE MARKING	
	PDIP – N	Tube of 25	SN74HC148N	SN74HC148N	
–40°C to 85°C		Tube of 40	SN74HC148D		
	SOIC – D	Reel of 2500	SN74HC148DR	HC148	
-40°C to 85°C		Reel of 250	SN74HC148DT		
	SOIC – DW	Reel of 2000	SN74HC148DWR	HC148	
	SOP – NS	Reel of 2000	SN74HC148NSR	HC148	
	CDIP – J	Tube of 25	SNJ54HC148J	SNJ54HC148J	
–55°C to 125°C	CFP – W	Tube of 150	SNJ54HC148W	SNJ54HC148W	
	LCCC – FK	Tube of 55	SNJ54HC148FK	SNJ54HC148FK	

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



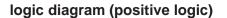
 $Copyright © 2004, \mbox{Texas Instruments Incorporated} \\ On products compliant to MIL-PRF-3853s, all parameters are tested unless otherwise noted. On all other products, production processing does not necessarily include testing of all parameters.$

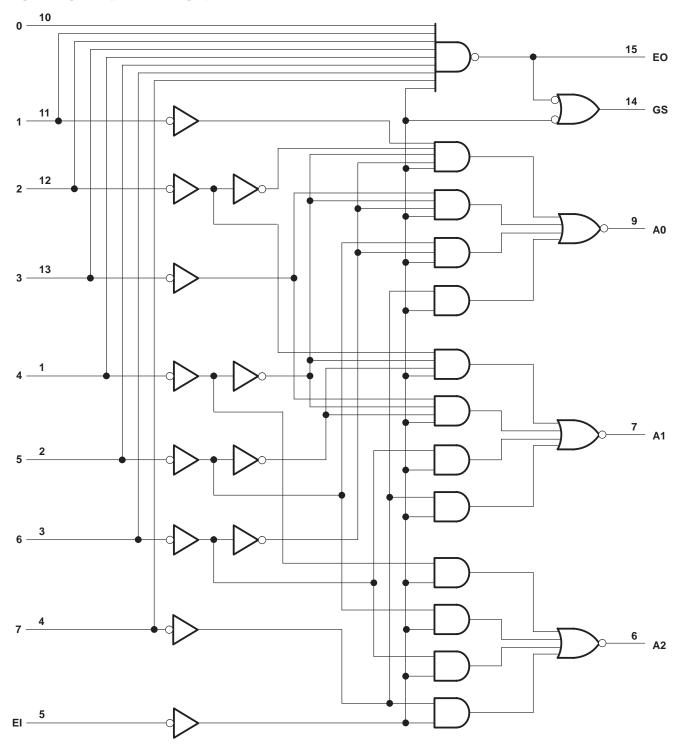
SCLS109G - MARCH 1984 - REVISED APRIL 2004

					F	UNCTIO	N TABL	E	_				
	INPUTS								OUTPUTS				
EI	0	1	2	3	4	5	6	7	A2	A1	A0	GS	EO
Н	Х	Х	Х	Х	Х	Х	Х	Х	Н	Н	Н	Н	Н
L	н	Н	Н	Н	Н	Н	Н	Н	н	Н	Н	н	L
L	Х	Х	Х	Х	Х	Х	Х	L	L	L	L	L	Н
L	Х	Х	Х	Х	Х	Х	L	Н	L	L	Н	L	Н
L	Х	Х	Х	Х	Х	L	Н	Н	L	Н	L	L	Н
L	Х	Х	Х	Х	L	Н	Н	Н	L	Н	Н	L	Н
L	Х	Х	Х	L	Н	Н	Н	Н	н	L	L	L	Н
L	Х	Х	L	Н	Н	Н	Н	Н	н	L	Н	L	Н
L	Х	L	Н	Н	Н	Н	Н	Н	н	Н	L	L	Н
L	L	Н	Н	Н	Н	Н	Н	Н	Н	Н	Н	L	Н



SCLS109G - MARCH 1984 - REVISED APRIL 2004





Pin numbers shown are for the D, DW, J, N, NS, and W packages.



SCLS109G - MARCH 1984 - REVISED APRIL 2004

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V_{CC} Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$) (see Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{CC}$)	e Note 1)	±20 mA
Continuous output current, $I_O (V_O < 0.01 V_O > V_{CC})$		
Continuous current through V_{CC} or GND		
Package thermal impedance, θ_{JA} (see Note 2):		
	DW package	57°C/W
	N package	67°C/W
	NS package	64°C/W
Storage temperature range, T _{stg}		–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

2. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions (see Note 3)

			SN	154HC14	18	SN	74HC14	8	
			MIN	NOM	MAX	MIN	NOM	MAX	UNIT
VCC	Supply voltage		2	5	6	2	5	6	V
		$V_{CC} = 2 V$	1.5			1.5			
VIH	High-level input voltage	$V_{CC} = 4.5 V$	3.15			3.15			V
		V _{CC} = 6 V	4.2			4.2			
		$V_{CC} = 2 V$			0.5			0.5	
VIL	Low-level input voltage	V _{CC} = 4.5 V			1.35			1.35	V
		V _{CC} = 6 V			1.8			1.8	
VI	Input voltage		0		VCC	0		VCC	V
VO	Output voltage		0		VCC	0		VCC	V
		$V_{CC} = 2 V$			1000			1000	
$\Delta t/\Delta v$	Input transition rise/fall time	V _{CC} = 4.5 V			500			500	ns
		V _{CC} = 6 V			400			400	
ТА	Operating free-air temperature		-55		125	-40		85	°C

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



SCLS109G - MARCH 1984 - REVISED APRIL 2004

				Т	A = 25°C	;	SN54H	IC148	SN74H	C148	
PARAMETER	TEST CO	ONDITIONS	Vcc	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
			2 V	1.9	1.998		1.9		1.9		
		I _{OH} = -20 μA	4.5 V	4.4	4.499		4.4		4.4		
VOH	$V_I = V_{IH} \text{ or } V_{IL}$		6 V	5.9	5.999		5.9		5.9		V
		$I_{OH} = -4 \text{ mA}$	4.5 V	3.98	4.3		3.7		3.84		
		I _{OH} = -5.2 mA	6 V	5.48	5.8		5.2		5.34		
			2 V		0.002	0.1		0.1		0.1	
		I _{OL} = 20 μA	4.5 V		0.001	0.1		0.1		0.1	
VOL	$V_{I} = V_{IH} \text{ or } V_{IL}$		6 V		0.001	0.1		0.1		0.1	V
		I _{OL} = 4 mA	4.5 V		0.17	0.26		0.4		0.33	
		I _{OL} = 5.2 mA	6 V		0.15	0.26		0.4		0.33	
li	$V_{I} = V_{CC} \text{ or } 0$		6 V		±0.1	±100		±1000		±1000	nA
ICC	$V_I = V_{CC} \text{ or } 0,$	IO = 0	6 V			8		160		80	μΑ
Ci			2 V to 6 V		3	10		10		10	pF

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

switching characteristics over recommended operating free-air temperature range, $C_L = 50 \text{ pF}$ (unless otherwise noted) (see Figure 1)

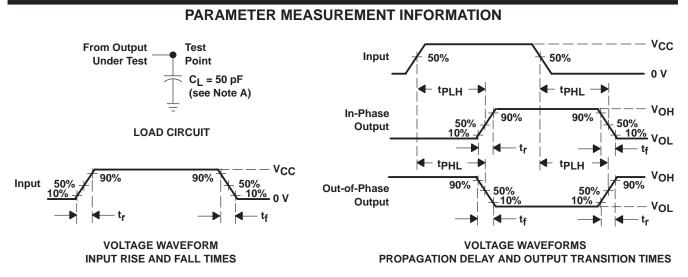
	FROM	то		T,	ς = 25°C	;	SN54H	IC148	SN74H	C148										
PARAMETER	(INPUT)	(OUTPUT)	vcc	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT									
			2 V		69	180		270		225										
	1–7	A0, A1, or A2	4.5 V		23	36		54		45										
			6 V		21	31		46		38										
			2 V		60	150		225		190										
		EO	4.5 V		20	30		45		38										
	0.7		6 V		17	26		38		33										
	0–7	GS	2 V		75	190		285		240										
			GS	4.5 V		25	38		57		48									
			6 V		21	32		48		41										
^t pd		A0, A1, or A2	2 V		78	195		295		245	ns									
			A0, A1, or A2	4.5 V		26	39		59		49									
				6 V		22	33		50		42									
			2 V		57	145		220		180										
	EI	GS	GS	GS	GS	GS	GS	4.5 V		19	29		44		36					
			6 V		16	25		38		31										
		EO	EO	EO	EO	EO	EO	EO	EO	EO	EO	2 V		66	165		250		205	
												EO	EO	EO	EO	EO	EO	4.5 V		22
			6 V		19	28		43		35										
					Any	Any	Any	Any 4	2 V		28	75		110		95				
tt									4.5 V		8	15		22		19	ns			
			6 V		6	13		19		16										



SCLS109G – MARCH 1984 – REVISED APRIL 2004

operating characteristics, T_A = 25°C

	PARAMETER	TEST CONDITIONS	TYP	UNIT
C _{pd}	Power dissipation capacitance	No load	35	pF



NOTES: A. CL includes probe and test-fixture capacitance.

- B. Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, Z_O = 50 Ω , t_r = 6 ns.
- C. The outputs are measured one at a time, with one input transition per measurement.
- D. tpLH and tpHL are the same as tpd.

Figure 1. Load Circuit and Voltage Waveforms

SCLS109G - MARCH 1984 - REVISED APRIL 2004



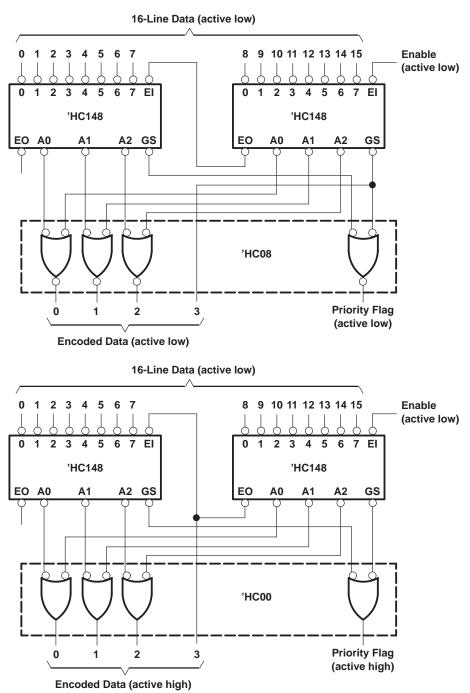


Figure 2. Priority Encoder for 16 Bits

Because the 'HC148 devices are combinational logic circuits, wrong addresses can appear during input transients. Moreover, a change from high to low at EI can cause a transient low on GS when all inputs are high. This must be considered when strobing the outputs.





9-Mar-2021

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SN54HC148J	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SN54HC148J	Samples
SN74HC148D	ACTIVE	SOIC	D	16	40	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC148	Samples
SN74HC148DE4	ACTIVE	SOIC	D	16	40	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC148	Samples
SN74HC148DG4	ACTIVE	SOIC	D	16	40	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC148	Samples
SN74HC148DR	ACTIVE	SOIC	D	16	2500	RoHS & Green	NIPDAU SN	Level-1-260C-UNLIM	-40 to 85	HC148	Samples
SN74HC148DRE4	ACTIVE	SOIC	D	16	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC148	Samples
SN74HC148DRG4	ACTIVE	SOIC	D	16	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC148	Samples
SN74HC148DT	ACTIVE	SOIC	D	16	250	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC148	Samples
SN74HC148N	ACTIVE	PDIP	Ν	16	25	RoHS & Green	NIPDAU	N / A for Pkg Type	-40 to 85	SN74HC148N	Samples
SN74HC148NSR	ACTIVE	SO	NS	16	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC148	Samples
SNJ54HC148FK	ACTIVE	LCCC	FK	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SNJ54HC 148FK	Samples
SNJ54HC148J	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SNJ54HC148J	Samples

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.



www.ti.com

9-Mar-2021

⁽³⁾ MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

⁽⁴⁾ There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

⁽⁵⁾ Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

⁽⁶⁾ Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

Important Information and Disclaimer:The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

OTHER QUALIFIED VERSIONS OF SN54HC148, SN74HC148 :

Catalog: SN74HC148

Military: SN54HC148

NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications

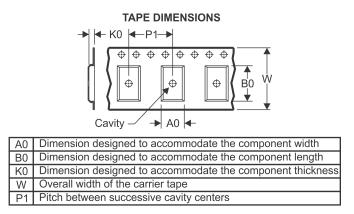
PACKAGE MATERIALS INFORMATION

www.ti.com

Texas Instruments

TAPE AND REEL INFORMATION





QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74HC148DR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
SN74HC148DR	SOIC	D	16	2500	330.0	16.8	6.5	10.3	2.1	8.0	16.0	Q1
SN74HC148DRG4	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
SN74HC148NSR	SO	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1

TEXAS INSTRUMENTS

www.ti.com

PACKAGE MATERIALS INFORMATION

30-Dec-2020



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74HC148DR	SOIC	D	16	2500	333.2	345.9	28.6
SN74HC148DR	SOIC	D	16	2500	364.0	364.0	27.0
SN74HC148DRG4	SOIC	D	16	2500	333.2	345.9	28.6
SN74HC148NSR	SO	NS	16	2000	853.0	449.0	35.0

LEADLESS CERAMIC CHIP CARRIER

FK (S-CQCC-N**) 28 TERMINAL SHOWN



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

- C. This package can be hermetically sealed with a metal lid.
- D. Falls within JEDEC MS-004



D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AC.



4211283-4/E 08/12

D (R-PDSO-G16) PLASTIC SMALL OUTLINE Stencil Openings (Note D) Example Board Layout (Note C) –16x0,55 -14x1,27 -14x1,27 16x1,50 5,40 5.40 Example Non Soldermask Defined Pad Example Pad Geometry (See Note C) 0,60 .55 Example 1. Solder Mask Opening (See Note E) -0,07 All Around

NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



MECHANICAL DATA

PLASTIC SMALL-OUTLINE PACKAGE

0,51 0,35 ⊕0,25⊛ 1,27 8 14 0,15 NOM 5,60 8,20 5,00 7,40 \bigcirc Gage Plane ₽ 0,25 7 1 1,05 0,55 0-10 Δ 0,15 0,05 Seating Plane — 2,00 MAX 0,10PINS ** 14 16 20 24 DIM 10,50 10,50 12,90 15,30 A MAX A MIN 9,90 9,90 12,30 14,70 4040062/C 03/03

NOTES: A. All linear dimensions are in millimeters.

NS (R-PDSO-G**)

14-PINS SHOWN

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



J (R-GDIP-T**) 14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- \triangle The 20 pin end lead shoulder width is a vendor option, either half or full width.



IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATASHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES "AS IS" AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, or other requirements. These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you will fully indemnify TI and its representatives against, any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI's products are provided subject to TI's Terms of Sale (https://www.ti.com/legal/termsofsale.html) or other applicable terms available either on ti.com or provided in conjunction with such TI products. TI's provision of these resources does not expand or otherwise alter TI's applicable warranties or warranty disclaimers for TI products.

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265 Copyright © 2021, Texas Instruments Incorporated